

ABSTRACT OF THE DISCLOSURE

SHEET FOR SEALING ELECTRONIC DEVICE AND METHOD FOR PRODUCING ELECTRONIC DEVICE PACKAGE

Provided is a sealing sheet for sealing an electronic device that is low in viscosity and that is a sheet in which an inorganic filler is filled into a high level. The sealing sheet is a sheet for sealing an electronic device which includes a compound having a methacryloxy group or acryloxy group as a silane coupling agent, and an inorganic filler in a proportion of 69 to 86% by volume. Furthermore, the sheet has a minimum viscosity ranging from 10 to 1000000 Pa·s.

FIG. 1